


FORM PTO-1449		Atty. Docket No.: V44.12-0149	Application No.: 09/970,074
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT		First Named Inventor: William D. Jensen	
		Filing Date: October 2, 2001	Group Art: 2816 2814

U.S. PATENT DOCUMENTS

Examiner Initial		Document No.	Date	Name	Class	Sub Class	Filing Date If Appropriate
AC	AA	Re. 32,625	3/15/1988	Schwarz et al.	374	57	8/18/1986
	AB	3,974,443	8/10/1976	Thomas	324	64	1/2/1975
	AC	4,024,561	5/17/1977	Ghatalia	H01L 29	78	4/1/1976
	AD	4,319,396	3/16/1982	Law et al.	29	571	12/28/1979
	AE	4,801,869	1/31/1989	Sprogis	324	73	4/27/1987
	AF	4,918,377	4/17/1990	Buehler et al.	324	691	12/5/1988
	AG	6,006,169	12/21/1999	Sandhu et al.	702	132	12/31/1997
	AH	6,028,756	2/22/2000	Freyman et al.	361	104	3/11/1998
	AI	6,108,804	8/22/2000	Derner	714	721	9/11/1997
	AJ	6,175,261 BI	1/16/2001	Sundaraman et al.	327	525	1/7/1999
AC	AK	6,211,745 BI	4/3/2001	Mucke et al.	331	117R	5/3/1999

FOREIGN PATENT DOCUMENTS

	Document No.	Date	Country	Class	Sub Class	Translation Yes No
AL						
AM						
AN						

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

AC	AO	V. Ryan, Acceleration of Stress-Migration Failure in Aluminum Interconnect, June 17, 1992, Pages 1-13.
AC	AP	V. Ryan, Enhanced Stress-Migration Reliability for ULSI Interconnect: An Insight into the Perils of Screening Al Depositions Based on Grain Size, 1995
AC	AQ	F.G. Yost, Stress-Voiding of Narrow Conductor Lines, 1990, pages 40-44

EXAMINER: Alonso Chambliss DATE CONSIDERED: 12/10/04

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.